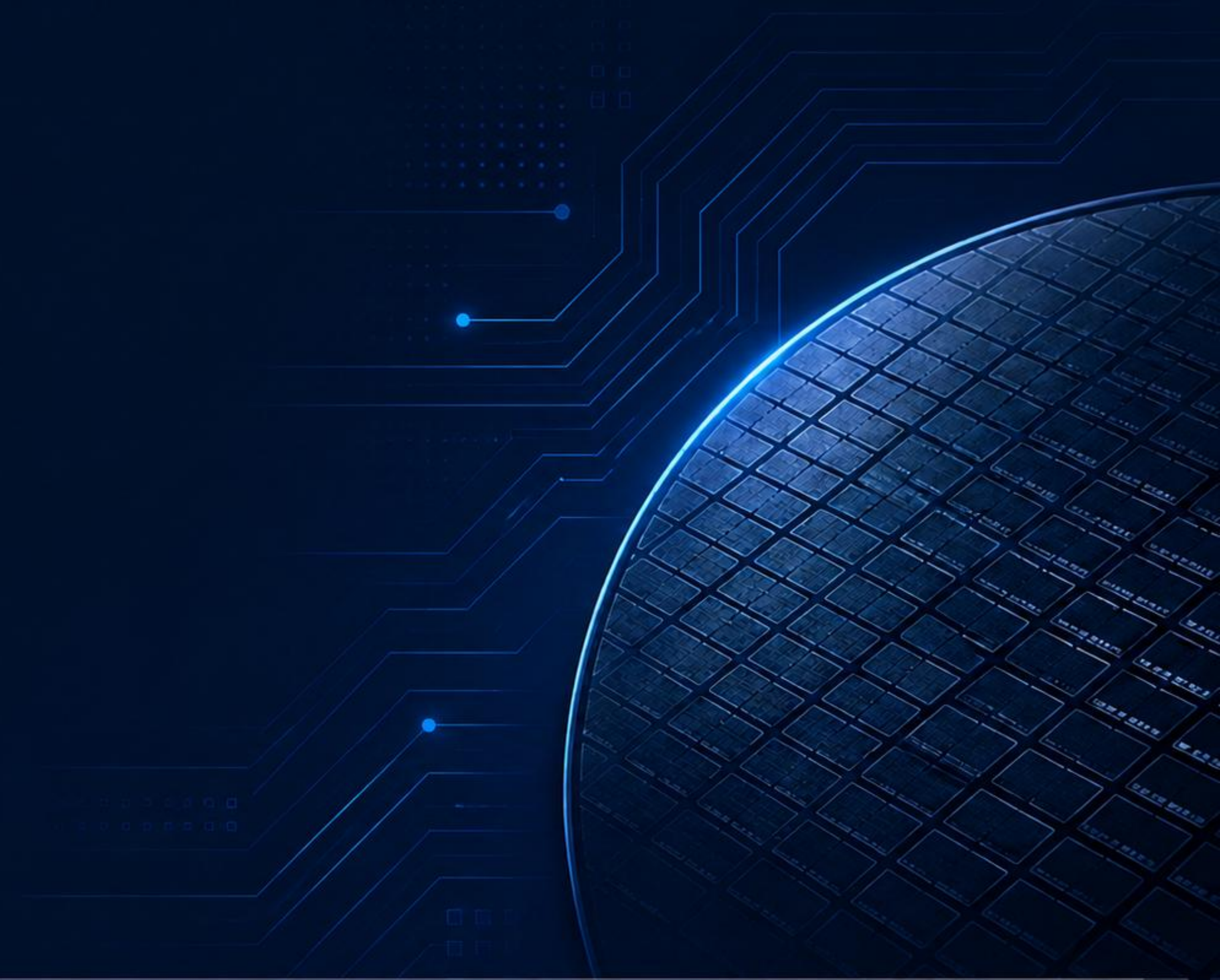
PSI



2026 First Quarter Earnings Conference

2Q 2026

Phoenix Silicon International Corporation

Safe Harbor Notice

PSI's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties, and actual results may differ materially from those contained in the forward-looking statements.

Information as to factors that could cause actual results to vary can be found in PSI's Annual or Quarterly Reports filed with the Taiwan Stock Exchange Corporation (TWSE), and in other documents that PSI may file with or submit to the TWSE from time to time.

Except as required by law, PSI undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

The figures in this presentation are prepared under IFRS.

What Makes PSI STAND OUT

01 THE MOST REWARDABLE

Leading Technology Innovator

- Advanced process capability drives margin content growth.
- Technology leadership delivers PSI's customer's best value.

Customer's Value Up

02 THE MOST SCALABLE

AI-Enabling Automation Pioneer

- Automation and AI improve PSI's productivity and execution consistency.
- Scalable capacity build-out supports sustainable growth in advance.

Operating Leverage

03 THE MOST ECO-FRIENDLY

Recycle, Reuse & Reduction Executor

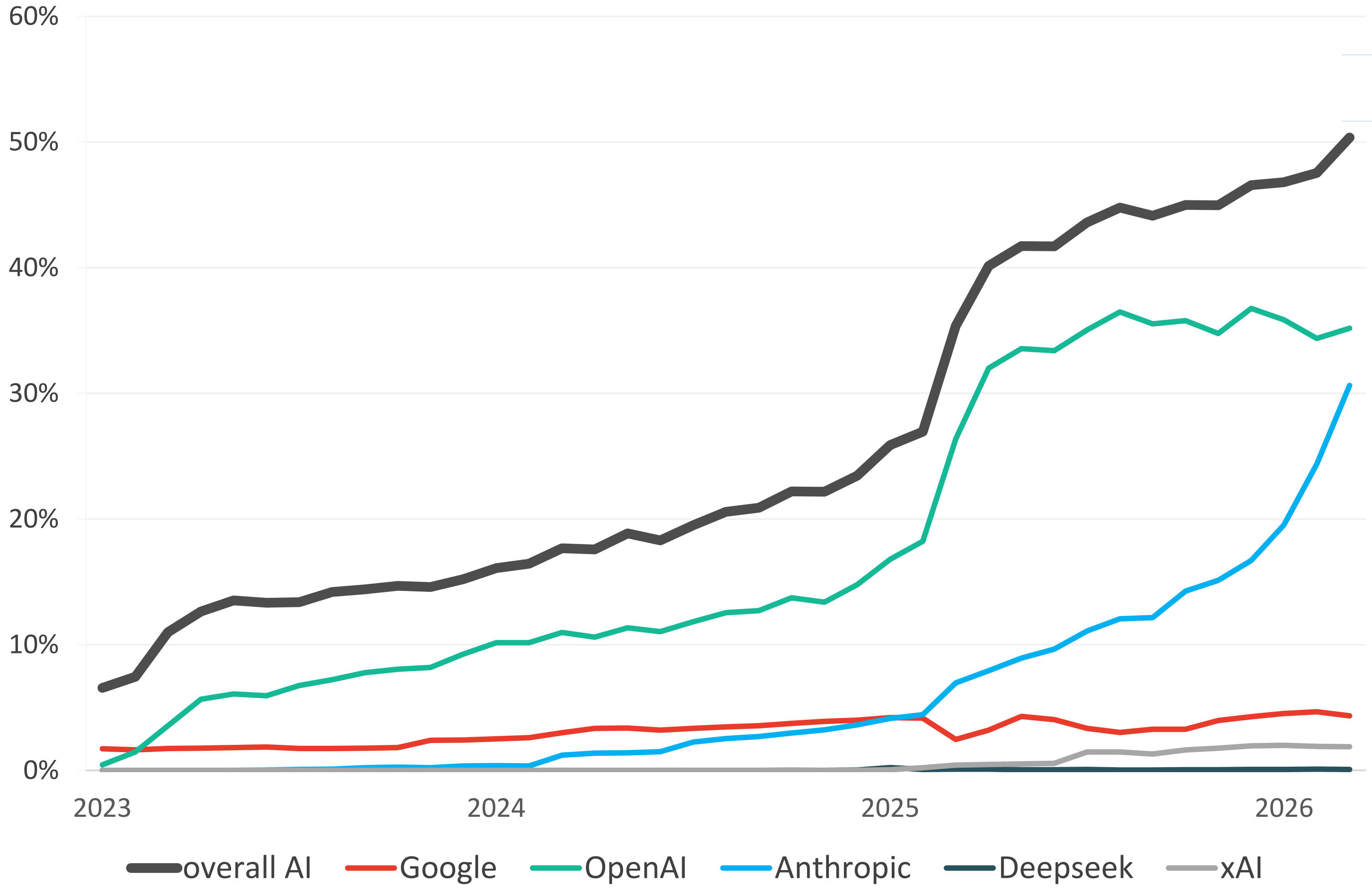
- Reclaim wafer business embeds ESG culture into PSI's operating core.
- Resource circulation efficiency improves long-term margin gains.

ESG Margin Added

Agenda

Presentation Overview

AI Adoption Rate Hiking



Latest Overall AI Adoption

50.4%

- AI adoption continues to accelerate.
- OpenAI remains the primary driver.
- Anthropic shows strong momentum.

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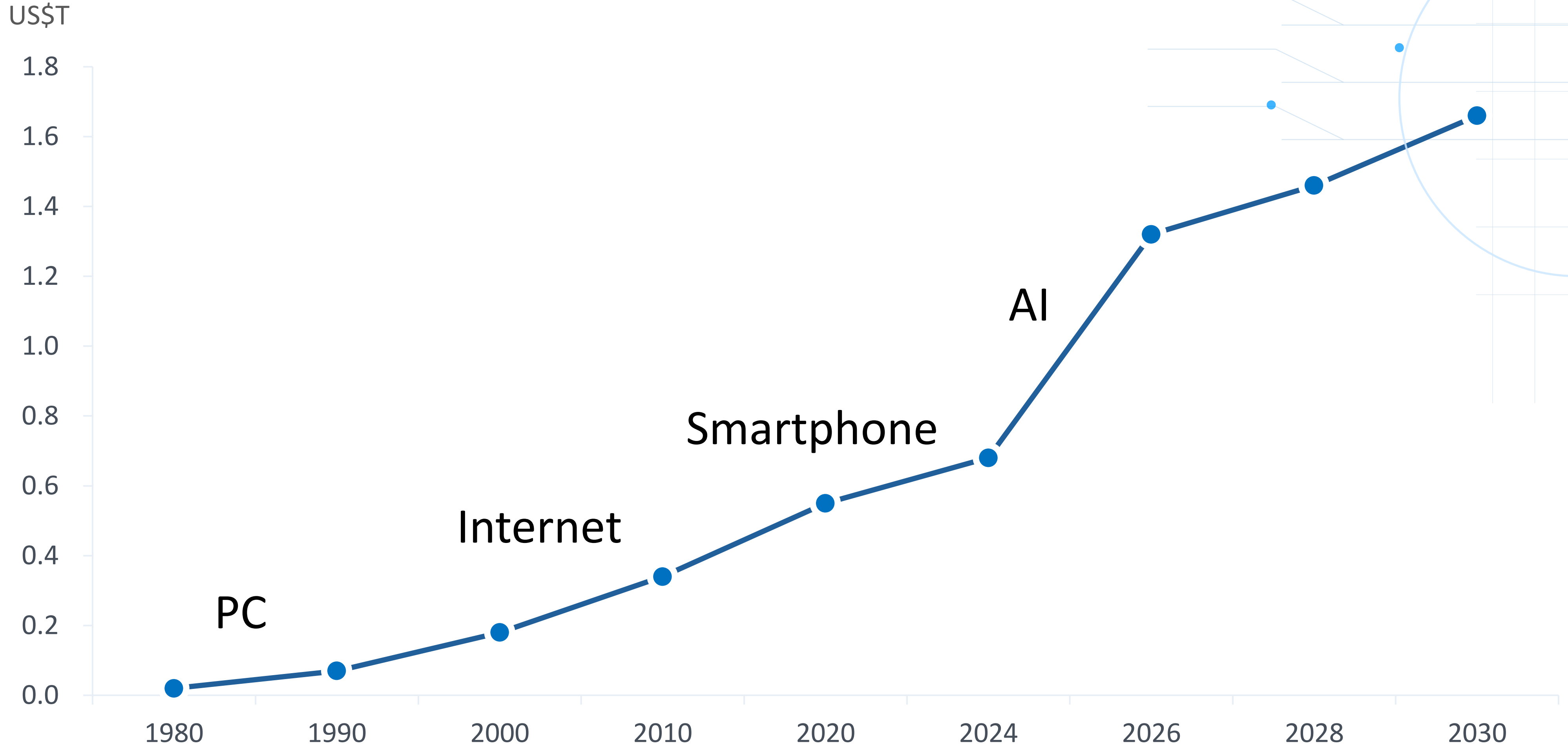
Source: Ramp AI index

AI Driving Semiconductor Outpace 1.5 Trillion USD



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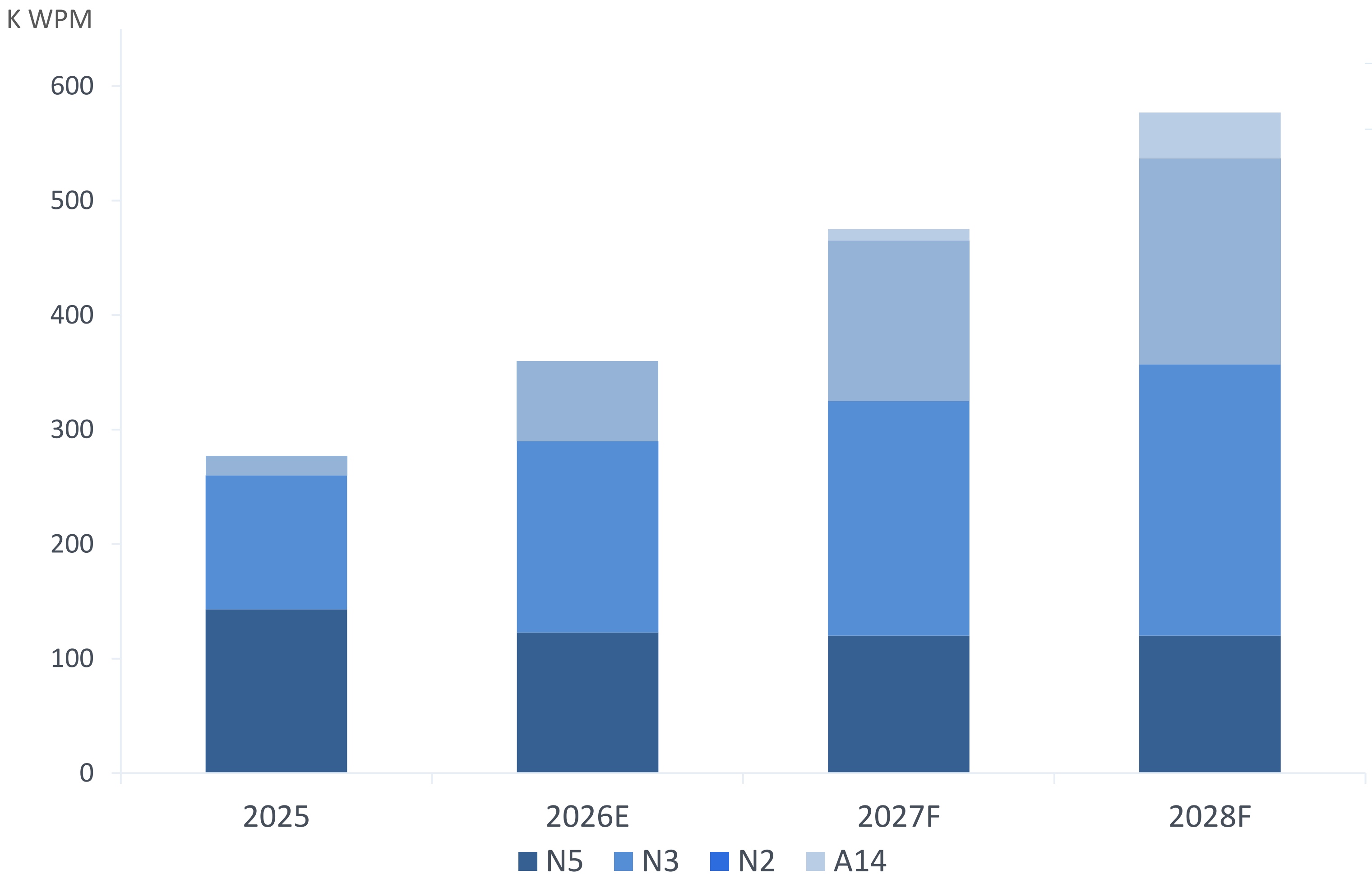
Source: Semi.Org, Gartner

Accelerating Advanced Node Expansion

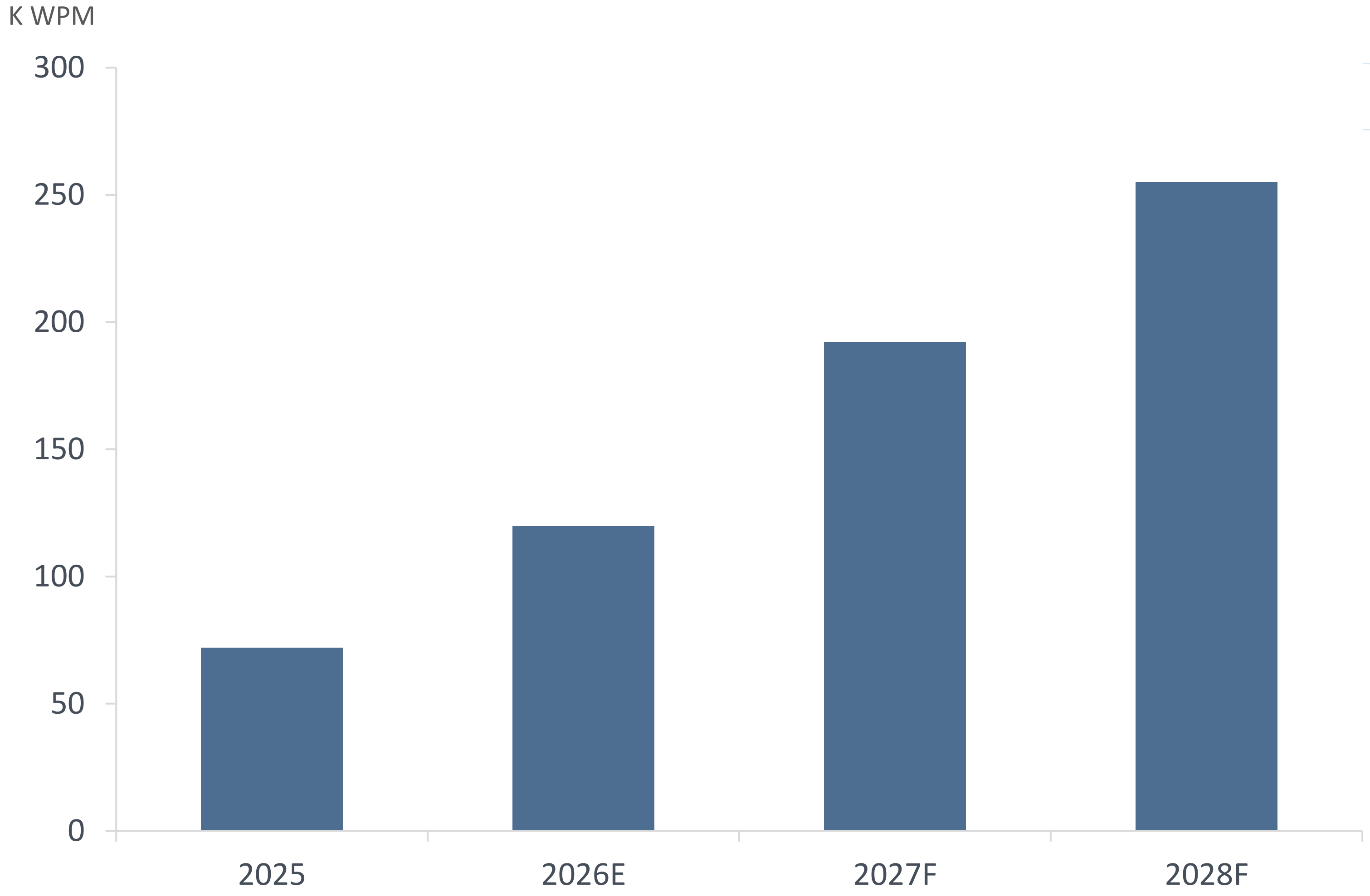


AI drives capacity expansion

CAGR 27.7%

Source: GS, UBS, PSI estimate

Revving Up Advanced Packaging



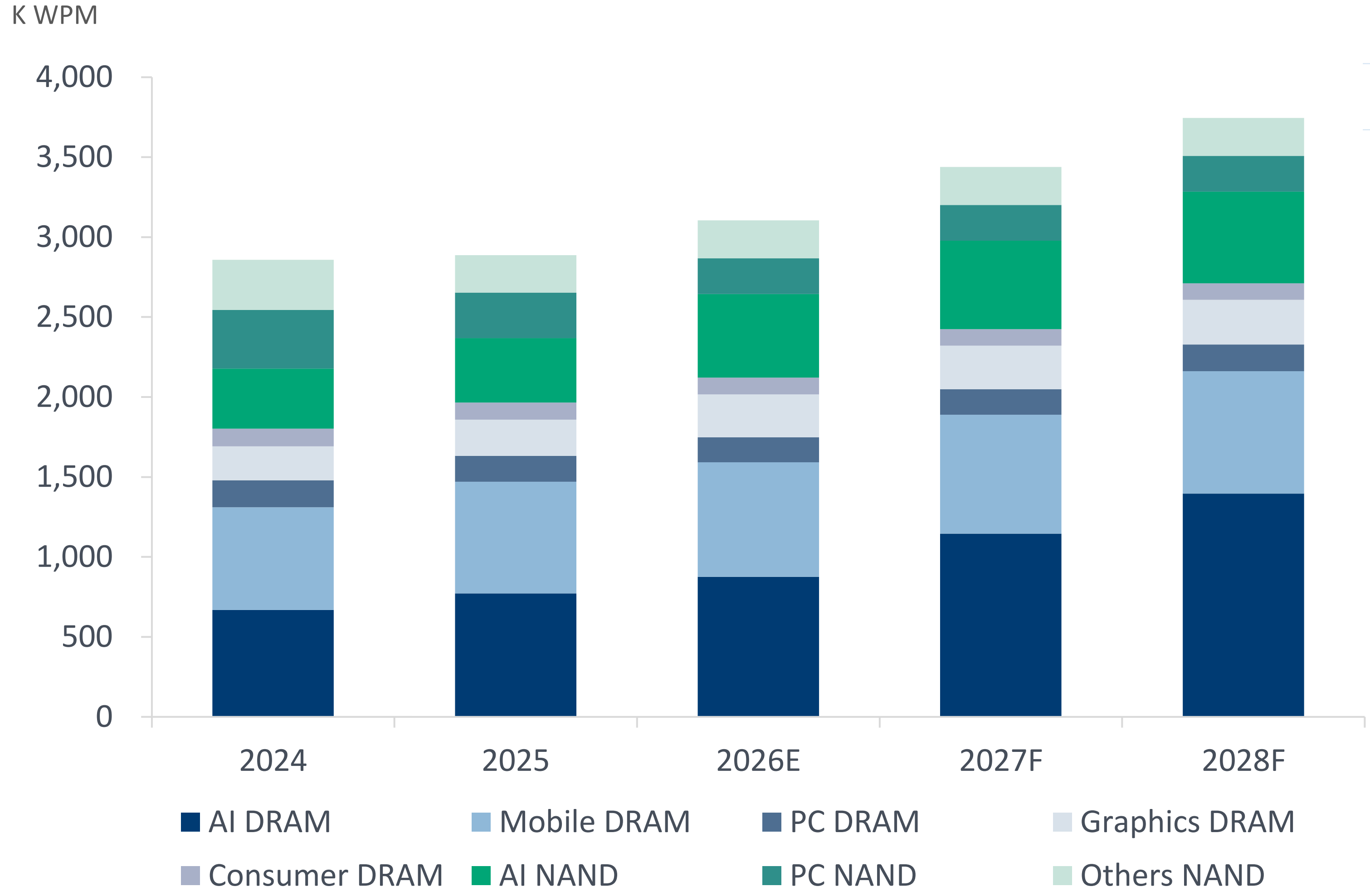
2.5 Packaging capacity

CAGR 52.5%

- 2.5 Packaging capacity growth underscores the intensity of AI-driven advanced packaging demand.

Source: GS, UBS, PSI estimate

Memory For AI Surging



Total CAGR

5.1%

AI DRAM CAGR

46.8%

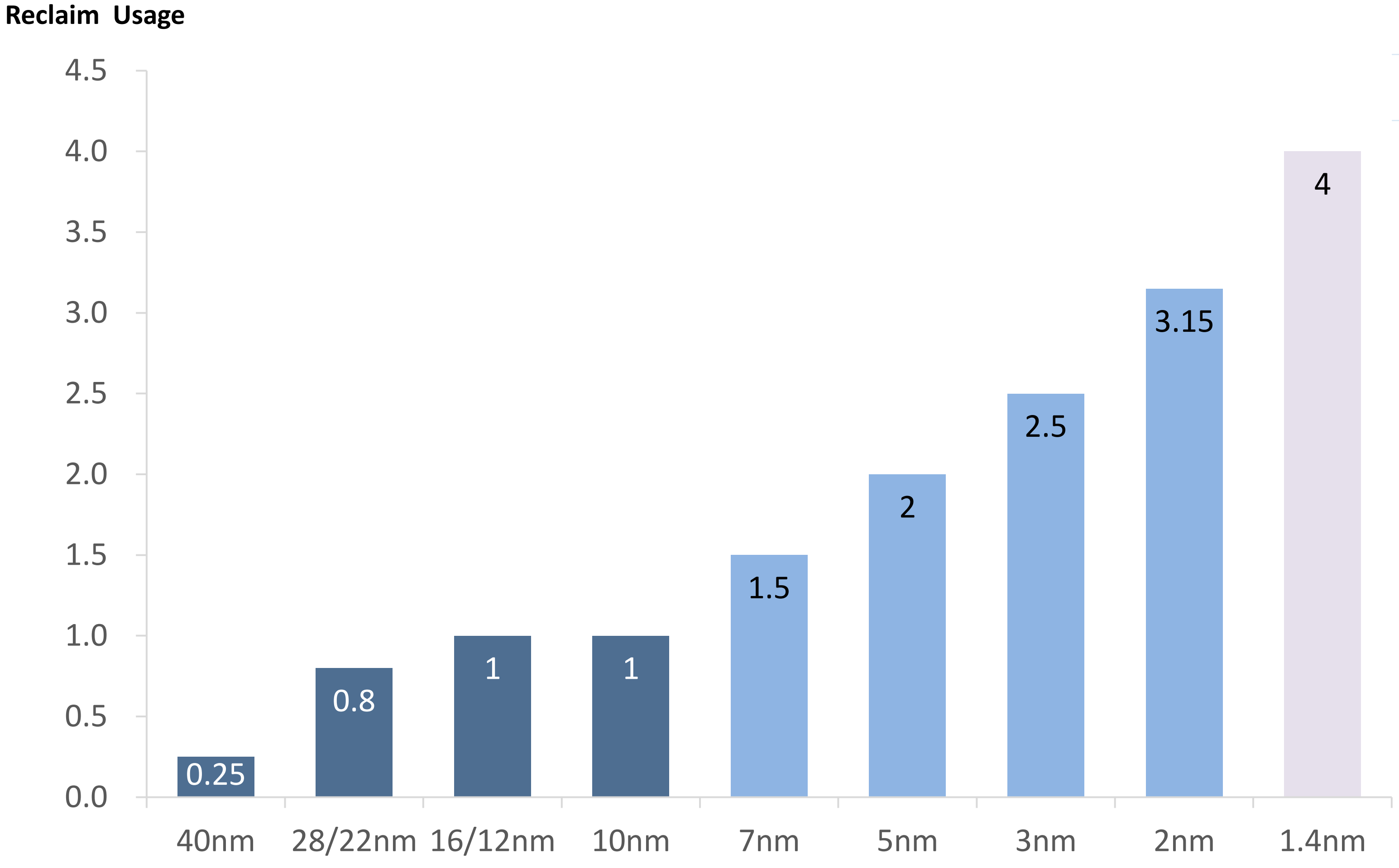
AI NAND CAGR

22.5%

Source: Sumco, GS , PSI estimate

Pillar I: Technology Leadership in Wafer Reclaim

Node Evolution & Reclaim Content



Reclaim Usage

Advanced-node reclaim usage is increasing, with four key specifications upgraded to support higher profit content.

Confidential

Source: UBS, PSI estimate

Reclaim Wafer Quality Metrics

Core Quality Indicators

1. **Particle Count & Size**

   Ensures surface cleanliness for advanced processes.

2. **Metal Contamination Level**

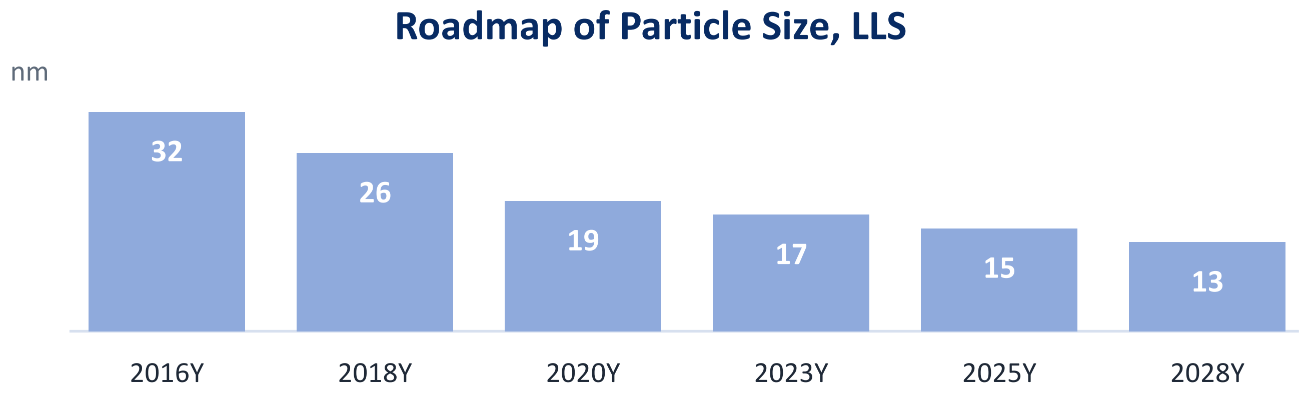
   Controls trace metals to protect reliability.

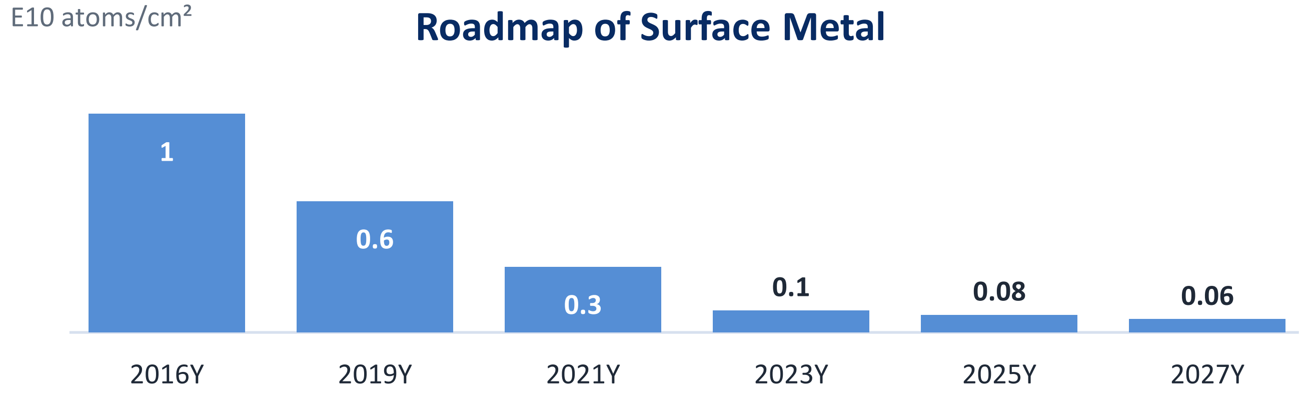
3. **Return Rate Yield**

   Measures reclaim yield and reuse efficiency.

4. **Surface Removal Amount**

   Controls removal depth and surface uniformity.





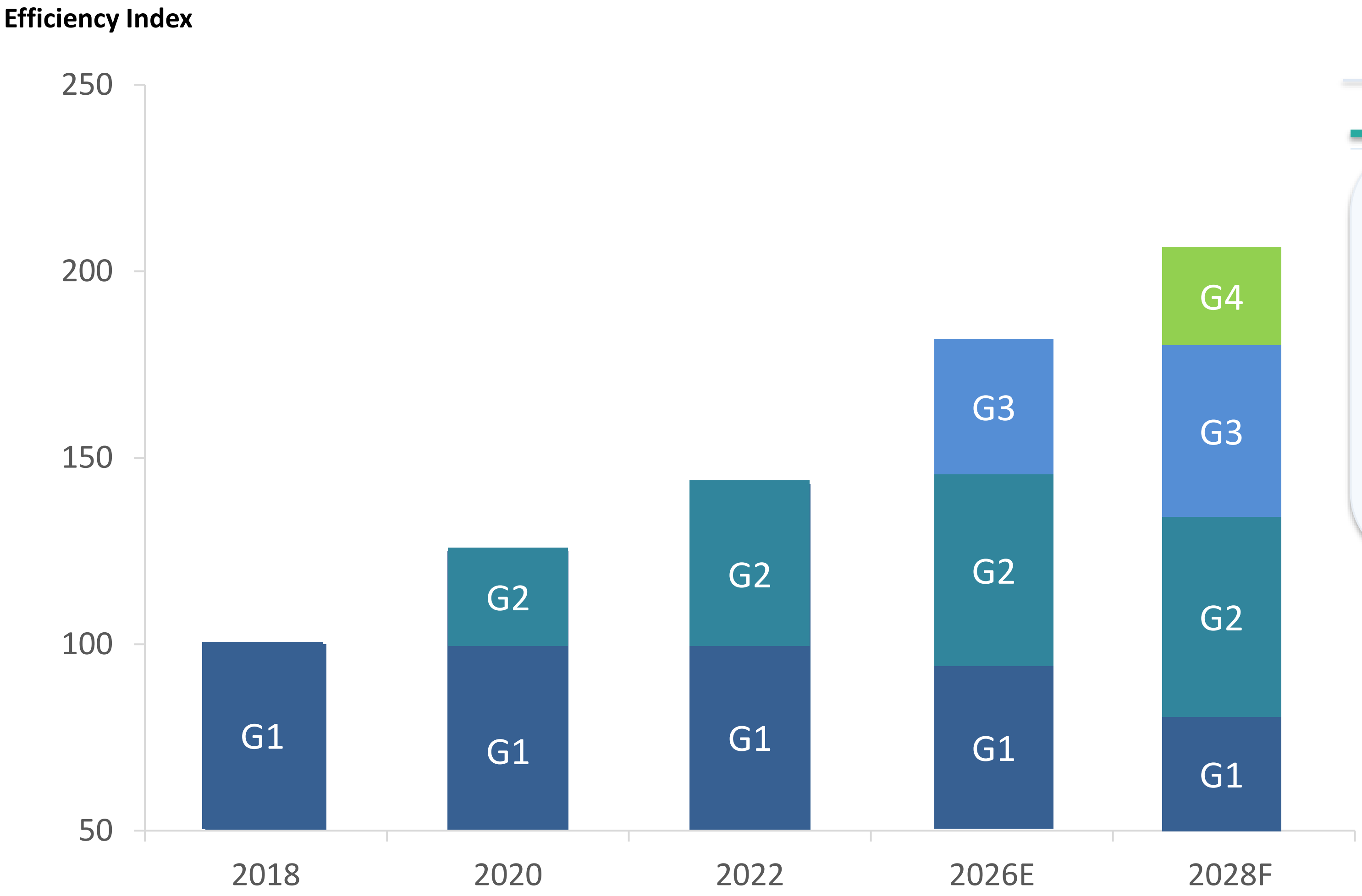
Source: PSI

Technology Evolution

Gen1 WIWO CMP	CMP → Water tank → CMP → Water tank → Cleaner	Conventional
Gen2 DIDO CMP	CMP → Cleaner → CMP → Cleaner	OHT Enabling
Gen3 GDP	Grinder → Dry Polisher → Cleaner	High Quality
Gen4 AP Stripper	Stripper → Cleaner	ECO Friendly

Source: PSI

Technology Deployment Roadmap



Reclaim Technology Node

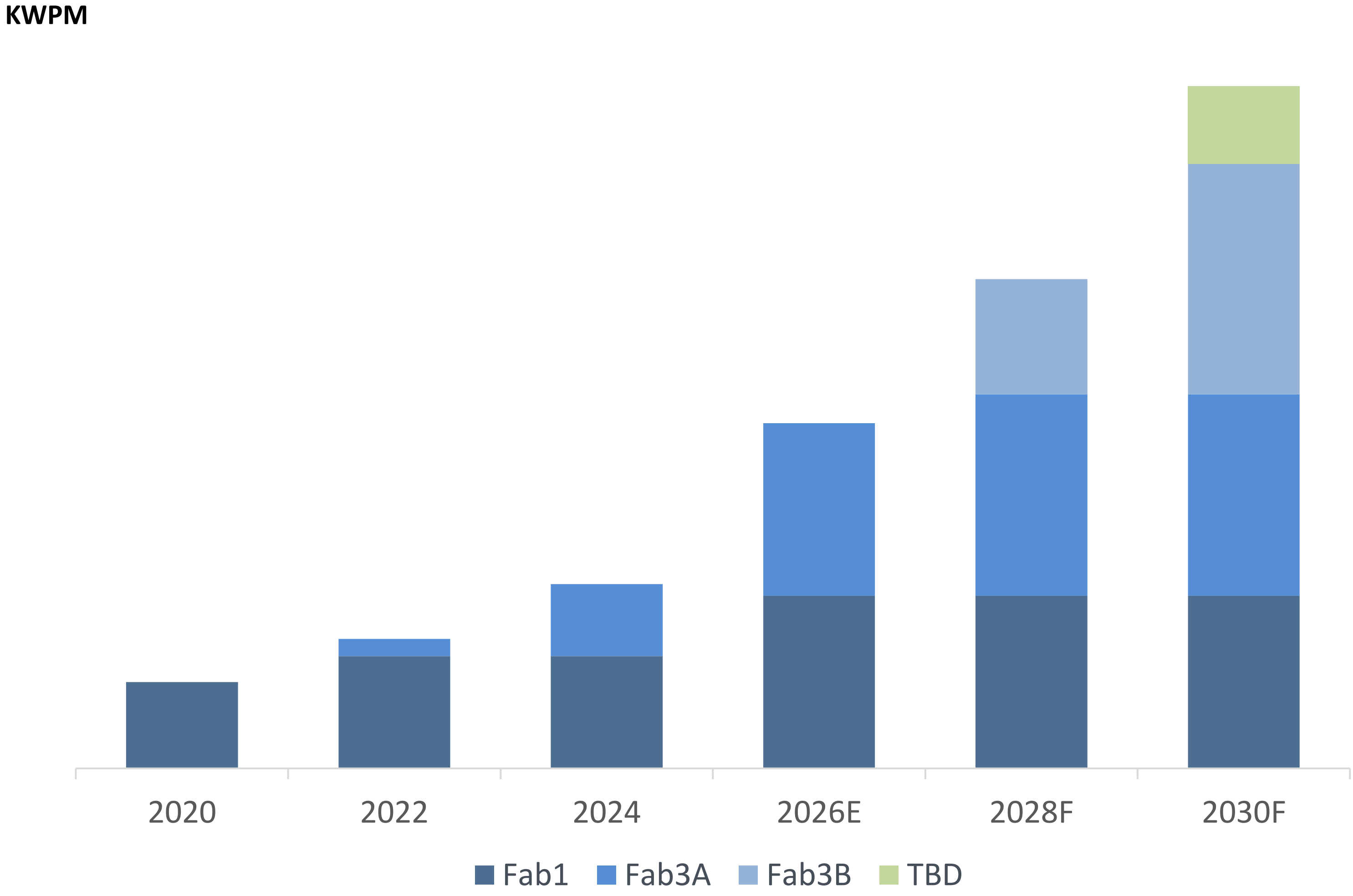
Gen 1: Wet-In, Wet-Out CMP
Gen 2: Dry-In, Dry-Out CMP
Gen 3: Grinder and Dry Polisher
Gen 4: Advanced Physical Stripper

Enhancing Efficiency and Effectiveness

- Rising output per depreciation
- Increasing output per employee

Source: PSI

Geo Capacity Expansion Plan

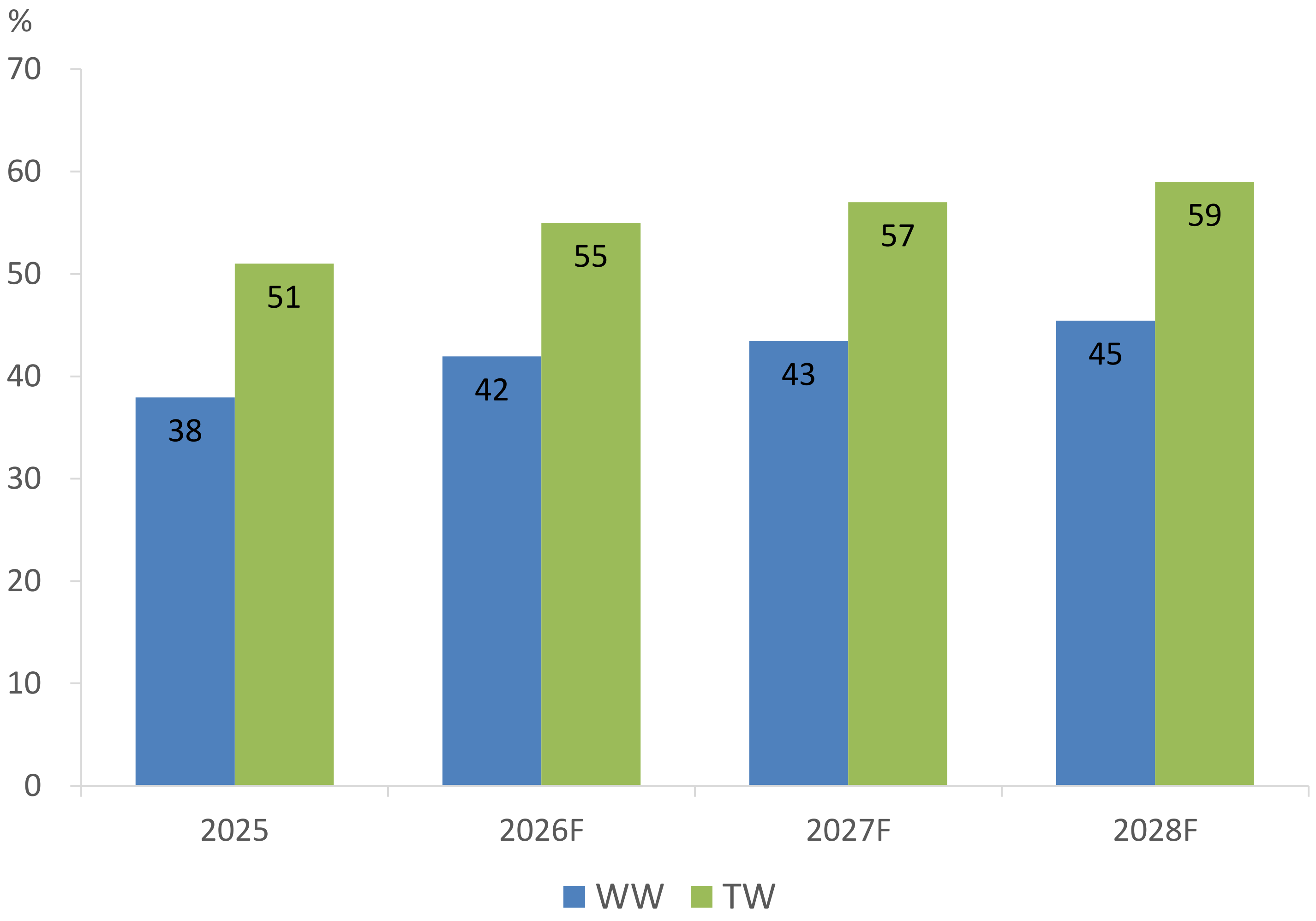


Key message

Capacity expansion provides the scale foundation for share gains, COGS improvement and operating leverage.

Source: PSI estimate

Market Share Quantity Base - Scale Up & Scale Out



2028 Market Share

WW 45% X TW 59%

PSI continues to expand share in both Taiwan and worldwide reclaim markets.

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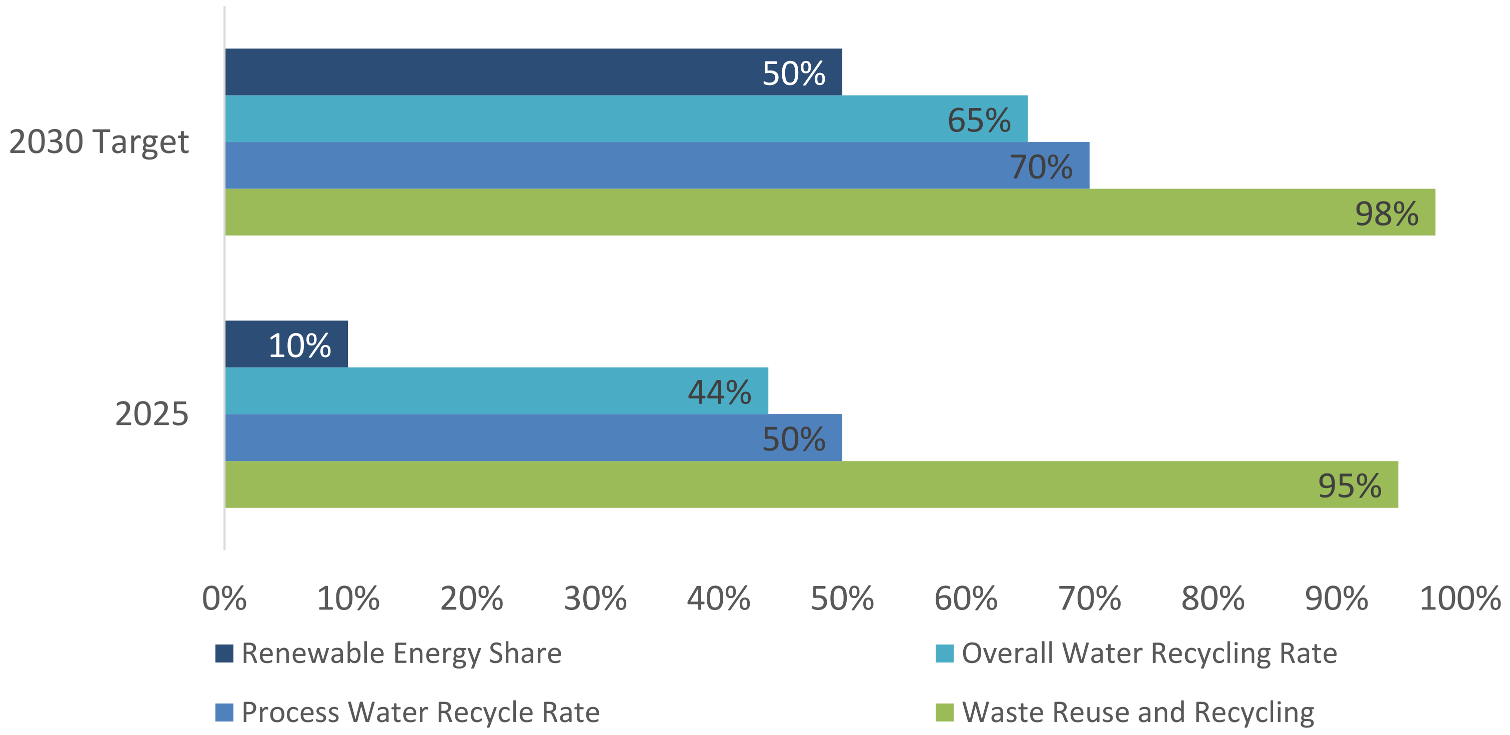
Source: PSI

ESG Margin Added



Key Message

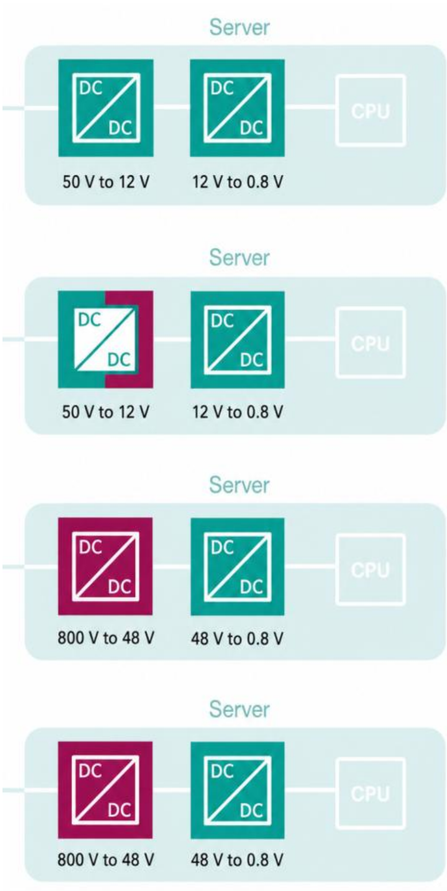
Technology innovation reduces input consumption, while recycle engineering improves recovery efficiency at the backend.

Resource efficiency creates long-term margin upside from the input and output ends.

Source: PSI

Pillar II: The Renaissance of Wafer Thinning

DRMOS Count for AI Trend

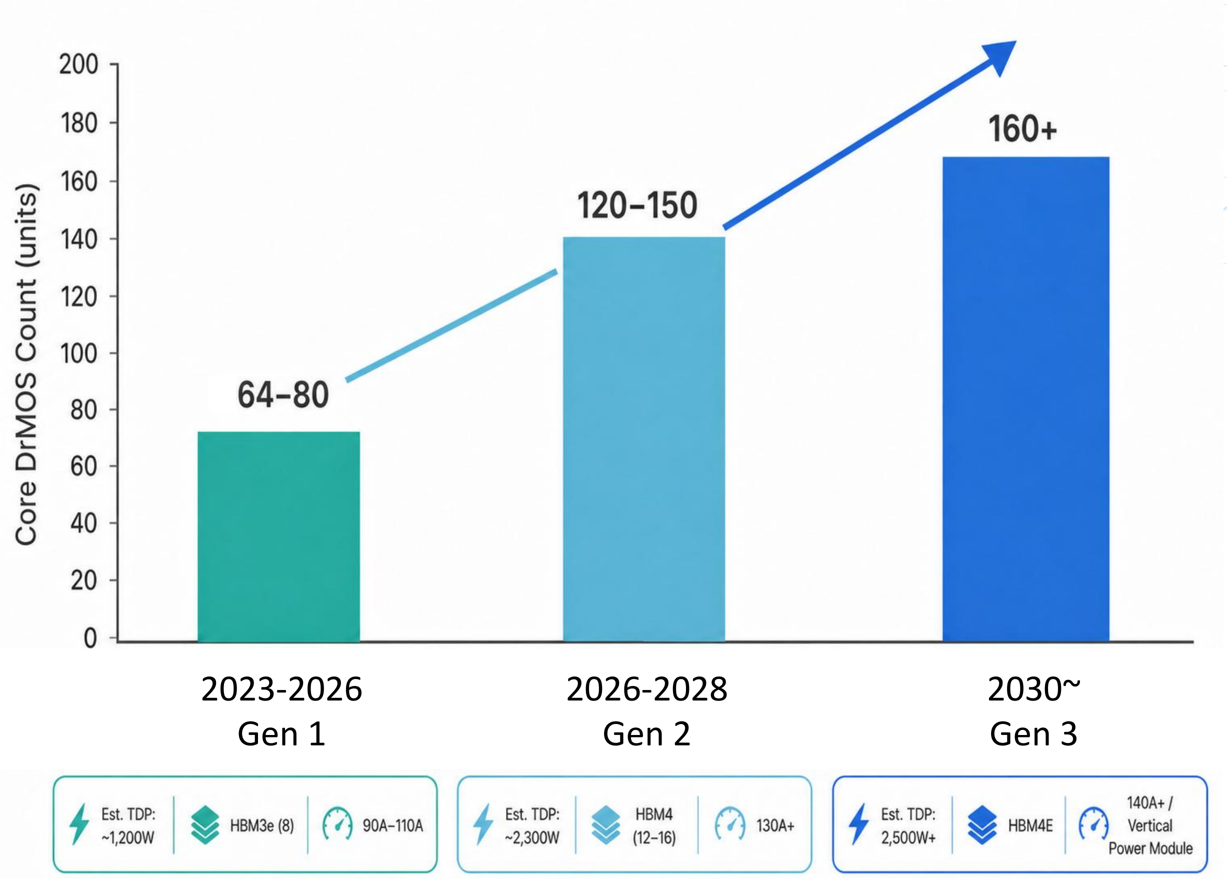


Gen 1
Today
Integrated IT rack
AC distribution

Gen 2a / 2b
50 V server
Disaggregated IT rack,
AC distribution

Gen 2c
Next gen 800 V server
Disaggregated IT rack,
AC distribution

Gen 3
Next gen 800 V server
Disaggregated IT rack,
DC distribution



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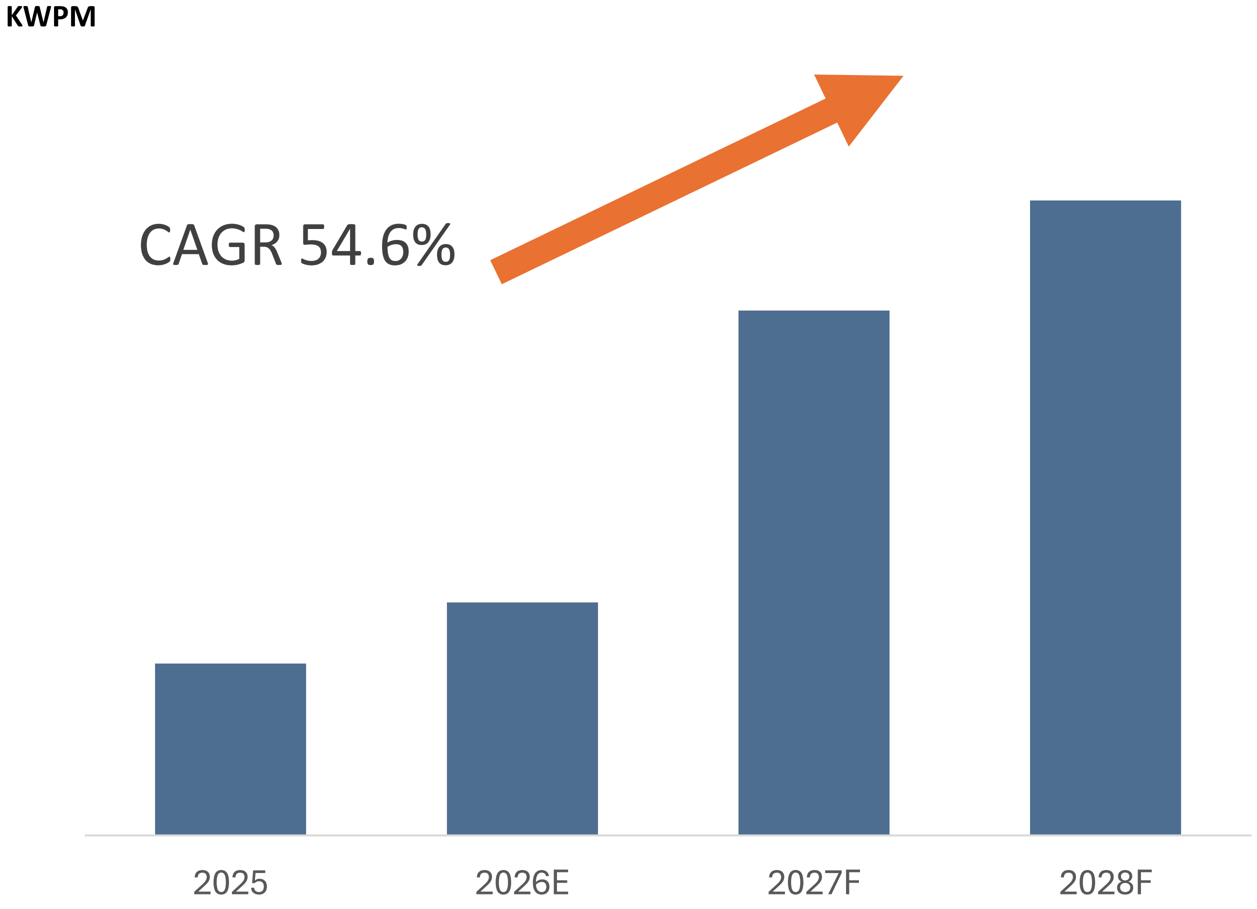
Source: Infineon, UBS, PSI estimate

IDM DRMOS Trend



Key message

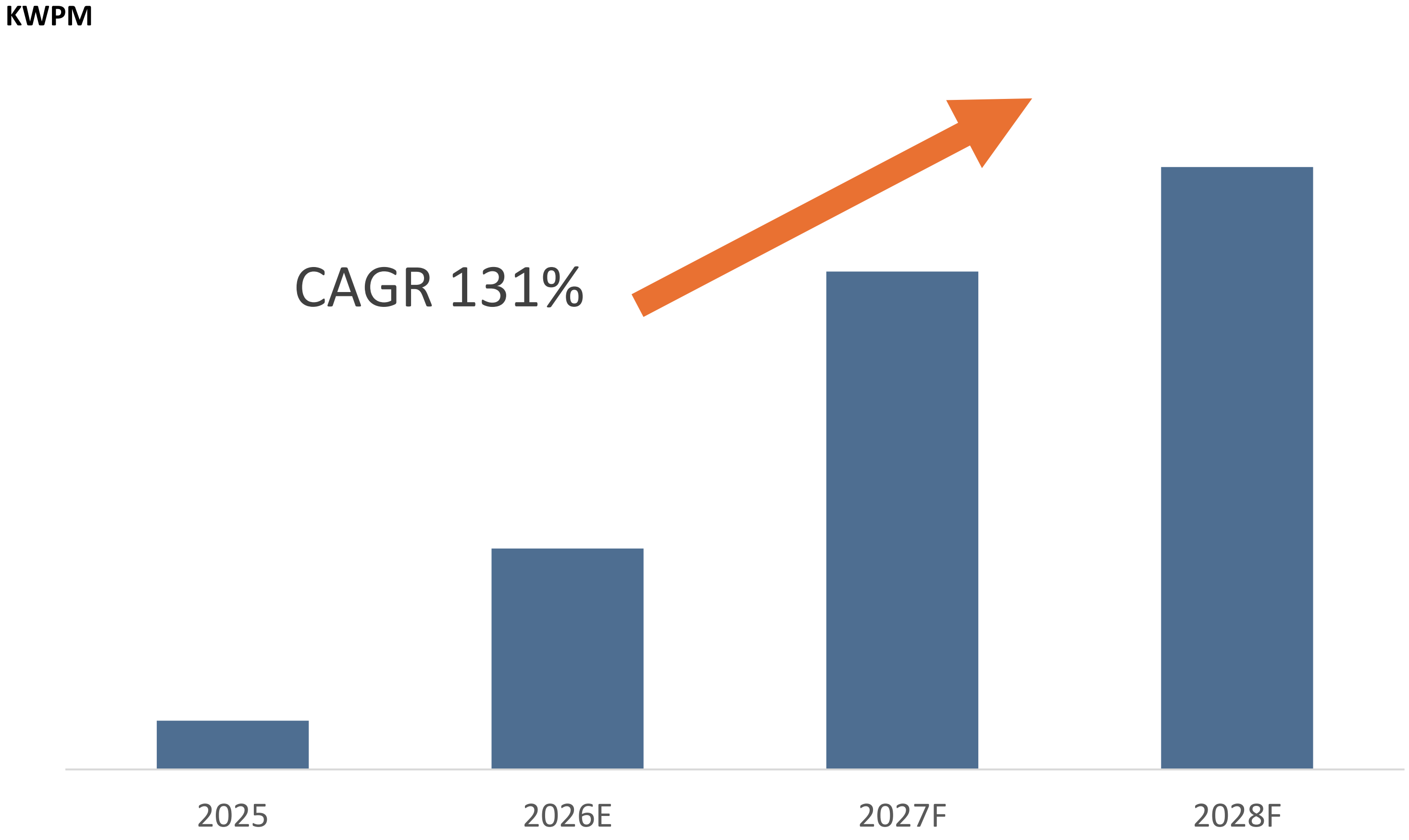
AI Server Growth

GROWING TAM

Higher GPU servers build-out drives demand for AI infrastructure, POWER management DRMOS.

Source: Macquarie, company data

PSI Power DRMOS Wafer Starts



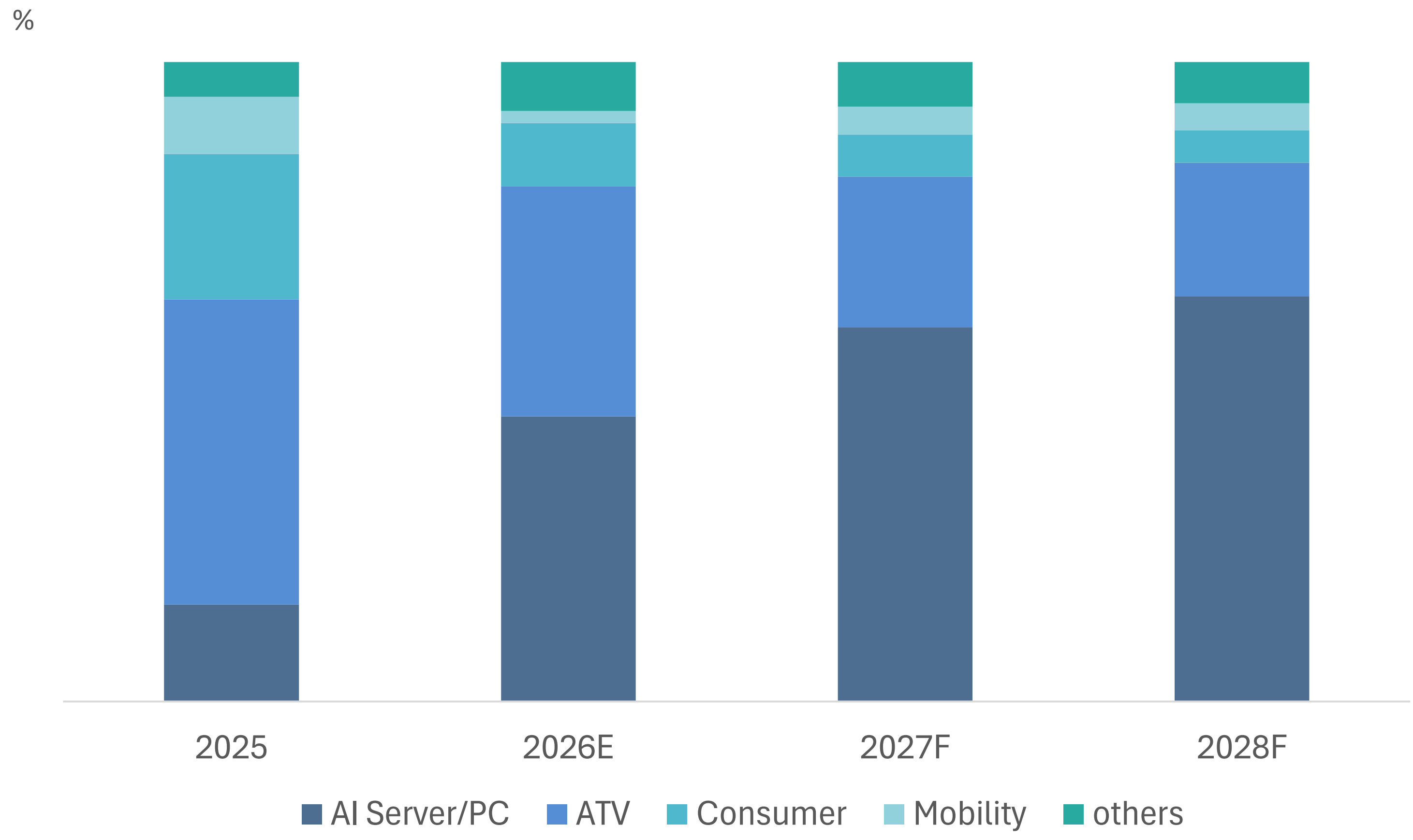
Key message

AI server power upgrades are accelerating Power DRMOS wafer starts and driving thinner (50um-32um), higher-value Taiko process demand.

Driving outsized growth via share gains within an accelerating TAM.

Source: PSI estimate

AI Driving PSI Thinning Higher Revenue Mix



Key message

CAGR 45%

AI Server and ATV are expected to account for 63% and 21% of revenue mix by 2028F, supporting margin is expected to double.

Source: PSI estimate

Pillar III: Advanced Material Solutions

AMS for Dummy Die / Thermal Dissipation / Warpage Control

AMS for Dummy / Thermal / Warpage

Si

Si – Dummy Die

Foundational Semiconductor Material

1) Mature & Scalable

- Large-area wafer growth
- Cost-effective, abundant, and well-established manufacturing.

2) Excellent Semiconductor

- High carrier mobility (~1350 $cm^2/V \cdot s$
- Ideal for high-speed, low-power electronics.

3) Moderate Bandgap

- Bandgap ~1.12 eV (indirect)
- Enables efficient electronic and optoelectronic devices.

4) Good Thermal Properties

- Thermal conductivity ~150 W/m·K
- Stable up to ~600 °C in inert environments.

SiC

SiC – Thermal Dissipation

High-Performance Material

1) Better Thermal Conductivity

- 260–450 W/m·K
- ~2–3x higher than Si

2) Mechanical Strength

- Mohs hardness ~9.2
- ~1.3x stronger than Si

3) Optical Transmission

- SiC: optimal at 0.4–2 µm
- Strong and durable

4) High Breakdown Field

- ~10x higher than Si
- Enables a thinner drift layer.

Al_2O_3

Al_2O_3 – Warpage Control

Advanced Ceramic Material

1) Single-Crystal Al_2O_3

- Sapphire-based mono substrate
- Suitable for laser de-bonding

2) Mechanical Hardness

- Excellent wear and abrasion resistance
- High strength and rigidity

3) Thermal Stability

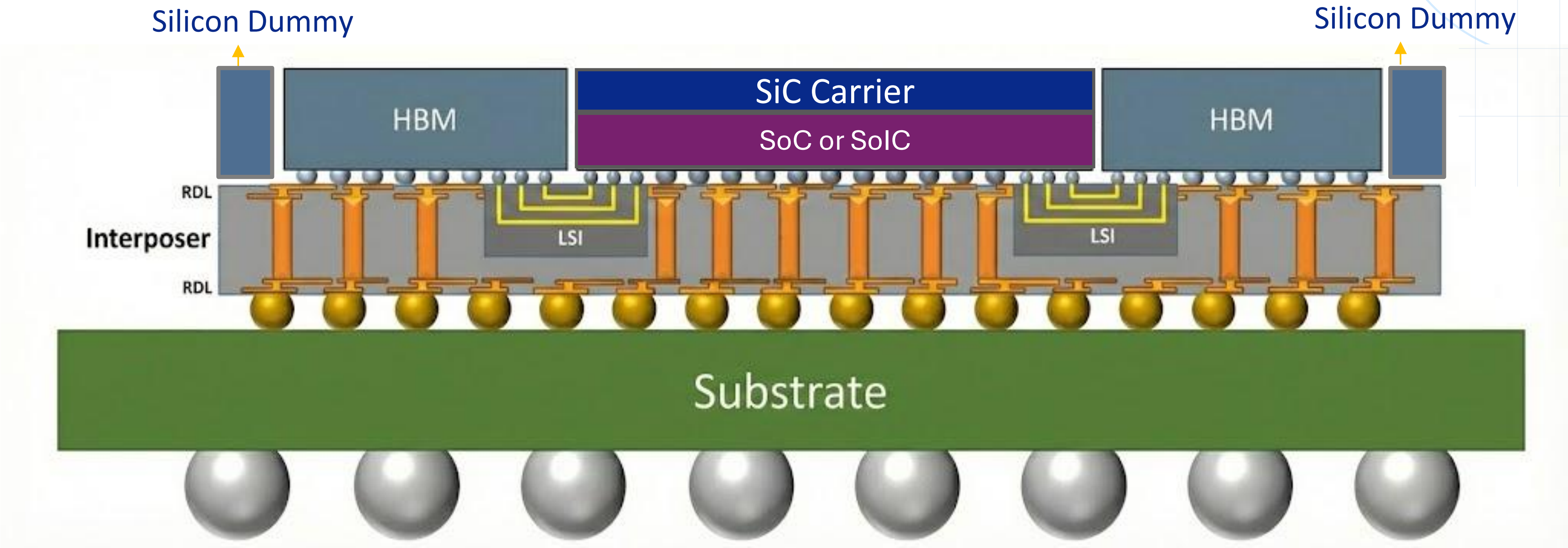
- Melting point ~2072 °C
- Good dimensional stability

4) Chemical Resistance

- Strong oxidation resistance
- Suitable for harsh environments

AMS- SiC for Thermal Dissipation / Si for Dummy Filler

- Substituting Si carriers with SiC to optimize thermal dissipation efficiency.
- Using Si dummy filler to enhance structural stability and packaging consistency.
- Adopting Al_2O_3 ceramic base to improve warpage control in substrate.



Source: company data, PSI

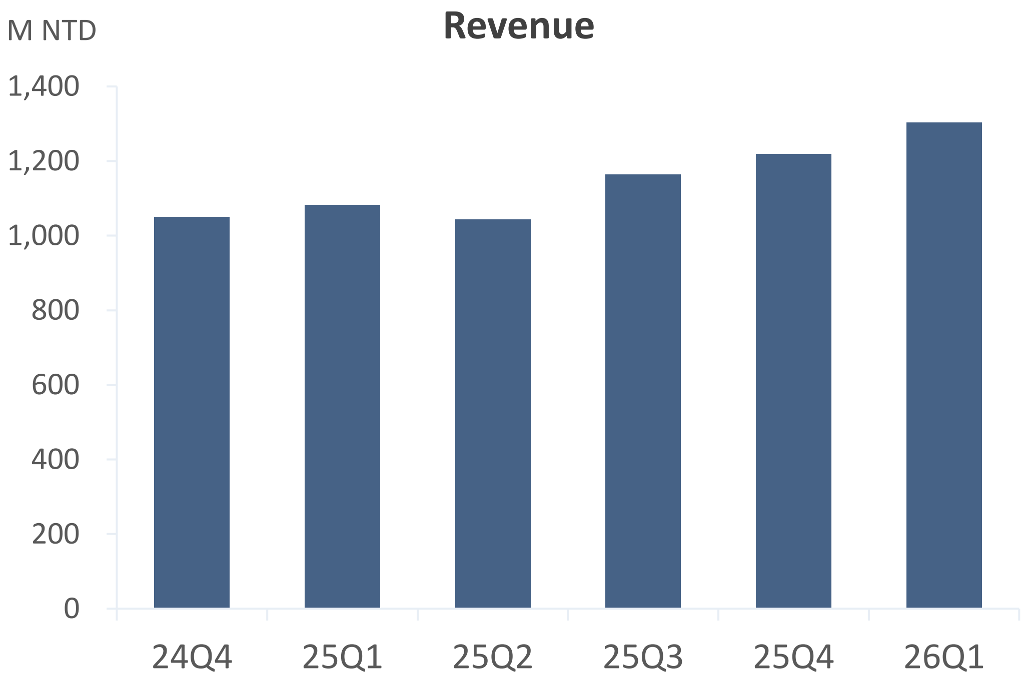
Financial Performance

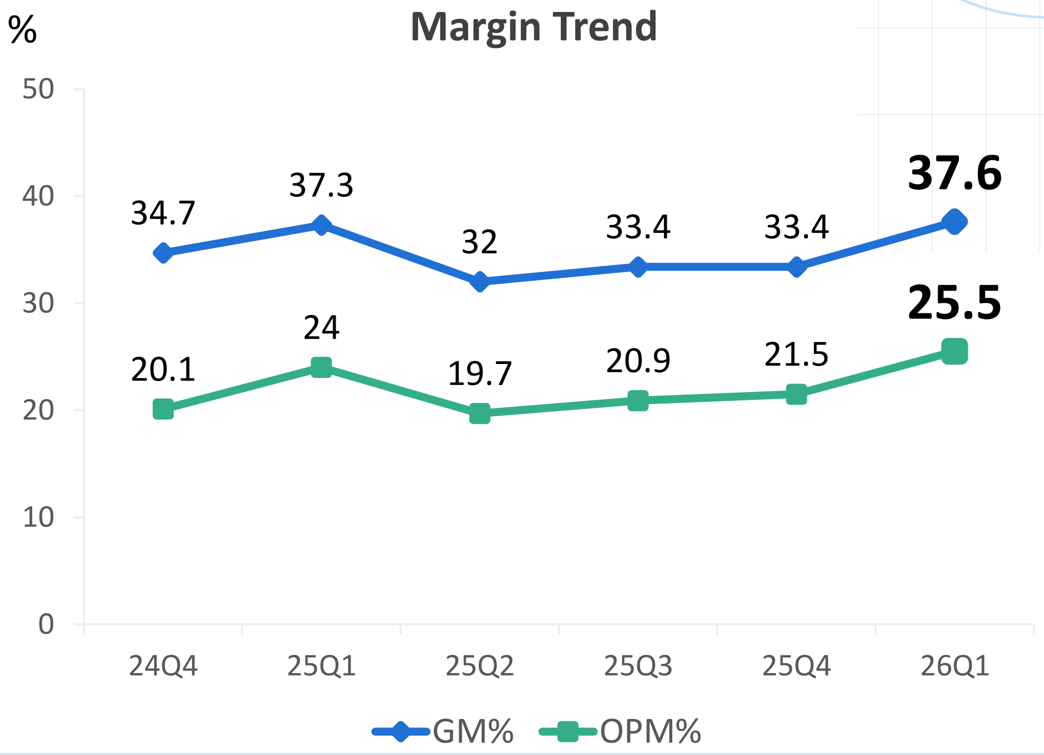
26Q1 Financial Highlights – Hit the Highest

Revenue
NT$ 1,303M

GPM
37.6%

OPM
25.5%





Financial Matrix

Item	2025Q1	2025Q4	206Q1	Y2024	Y2025
Shipment (Kpcs, 12"-equiv. Wafer)	2,099	2,599	2,636	6,869	9,486
Net Revenue (US$ Millions)	33	39	41	110	144
Net Revenue (NT$ Millions)	1,082	1,219	1,303	3,551	4,509
Gross Margin	37.3%	33.4%	37.6%	28.8%	34.0%
Operating Margin	24.3%	21.5%	25.5%	15.1%	21.5%
Net Profit Margin	21.3%	18.4%	22.0	15.7%	16.8%
EPS (NT$)	1.34	1.29	1.61	2.85	4.37
ROE (annualized)	21.1%	18.3%	21.7%	12.2%	16.4%
Operating Cash Flow (NT$ M)	426	410	263	1,491	1,401
Capital Expenditures (NT$ M)	944	-1,135	-669	-1,364	-3,180
Free Cash Flow (NT$ M)	-518	-723	-406	126	-1,779

PSI

Key Takeaways

Key Takeaways

- PSI is benefitted from AI's booming semiconductor demand with a high growth cycle from frontend advanced node to backend advanced packaging.
- PSI is leading through three strategic pillars: innovative wafer reclaim, uplifting Power thinning, advanced materials solutions.
- PSI's long standing competitive moats are built on technologies in process quality, operation efficiency and environmental sustainability.

Psi

Promise · Sustainable · Innovation

The most rewardable

Leading Technology Innovator

The most scalable

AI-Enabling Automation Pioneer

The most eco-friendly

Recycle, Reuse & Reduction Executor

Innovate Today, Sustain Tomorrow, Create Value Together.

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